

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-12V	13mΩ@-4.5V	-16A
	16mΩ@-2.5V	

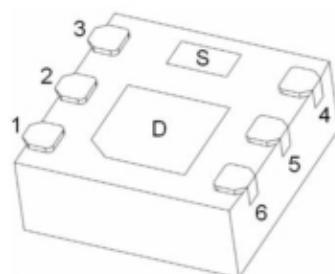
## Feature

- Advanced trench MOSFET process technology
- Ultra low on-resistance with low gate charge

## Applications

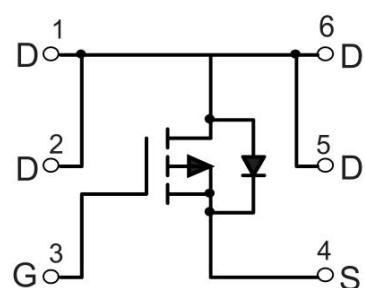
- PWM application
- Load switch
- Battery charge in cellular handset

## Package



**DFNWB2\*2-6L-J**

## Circuit diagram

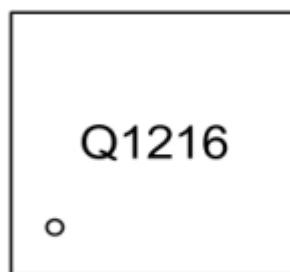




ZL MOSFET

ZL1216

## Marking



**Q1216 =Device Code**

## Order information

Device	Package	Shipping
SP1216NQ	DFN2*2-6L	4000/Tape&Reel

## Absolute maximum ratings

( $T_a=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source Voltage	$V_{DS}$	-12	V
Gate-source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current  $T_c=25^\circ\text{C} @ \text{Steady State}$	$I_D$	-16	mA
		-12.8	
Pulsed Drain Current <sup>1</sup>	$P_D$	-64	mW
Total Power Dissipation @ $T_c=25^\circ\text{C}$	$R_{\theta JC}$	18	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case @ Steady State	$T_J$	6.9	$^\circ\text{C}$
Junction and Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

## Electrical characteristics

( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-12			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -12\text{V}, V_{GS} = 0\text{V}, T_C = 25^\circ\text{C}$			-1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	$\mu\text{A}$
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = -4.5\text{V}, I_D = -10\text{A}$		13	18	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -6.5\text{A}$		16	22	
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		2050		$\text{pF}$
Output capacitance	$C_{oss}$			411		
Reverse transfer capacitance	$C_{rss}$			362		
<b>Switching Characteristics</b>						
Total gate charge	$Q_g$	$V_{GS} = -10\text{V}, V_{DS} = -12\text{V}, I_D = -9.1\text{A}$		30		$\text{nC}$
Gate-source charge	$Q_{gs}$			5.3		
Gate-drain charge	$Q_{gd}$			7.6		
Turn-on Delay Time	$T_{d(on)}$	$V_{GS} = -10\text{V}, V_{DS} = -12\text{V}, I_D = -6\text{A}, R_G = 2.5\Omega$		14		$\text{nS}$
Turn-on Rise Time	$T_r$			20		
Turn-Off Delay Time	$T_{d(off)}$			95		
Turn-Off Fall Time	$t_f$			65		
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$I_S = -1\text{A}, V_{GS} = 0\text{V}$		0.8	-1.2	V
Maximum Body-Diode Continuous Current	$I_S$				-13	A

### Note:

- Repetitive Rating: Pulse width limited by maximum junction temperature.

## Typical Characteristics

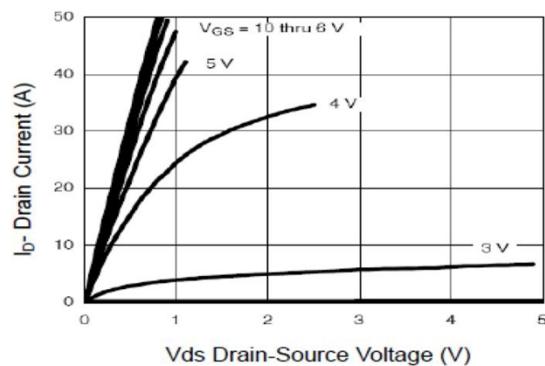


Figure1. Output Characteristics

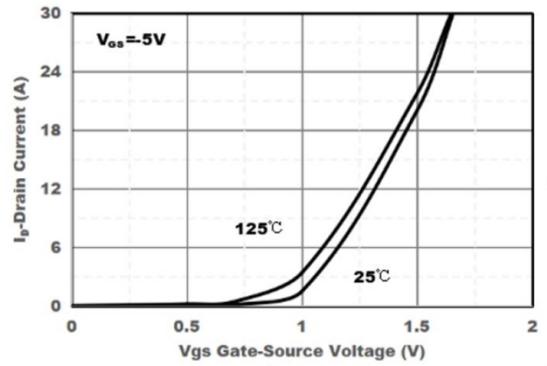


Figure2. Transfer Characteristics

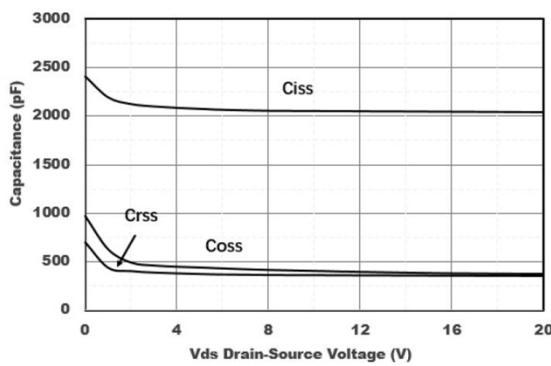


Figure3. Capacitance Characteristics

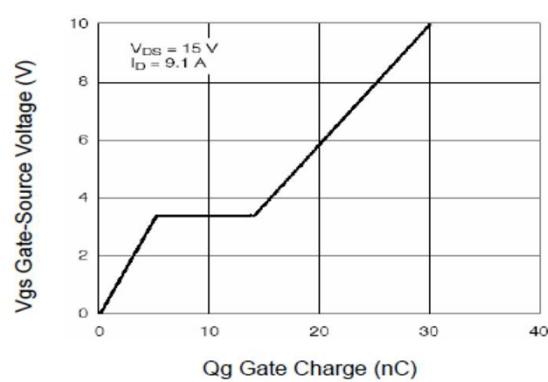


Figure4. Gate Charge

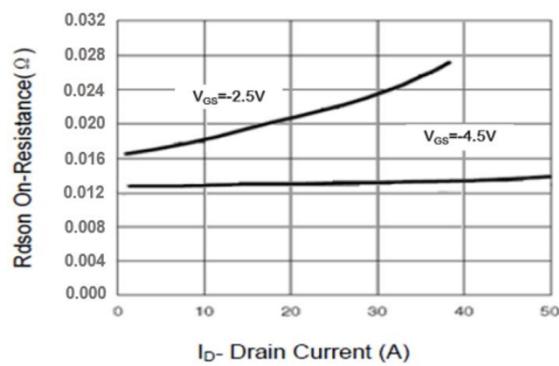


Figure5. Drain-Source on Resistance

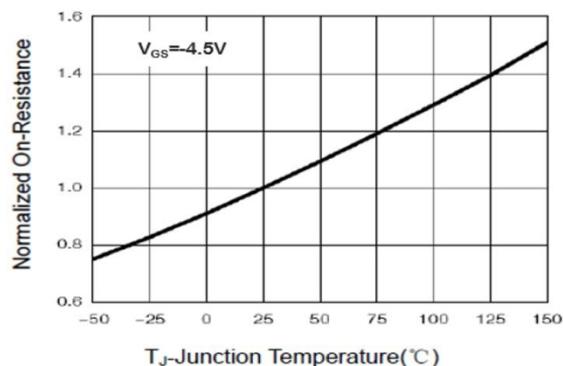


Figure6. Drain-Source on Resistance

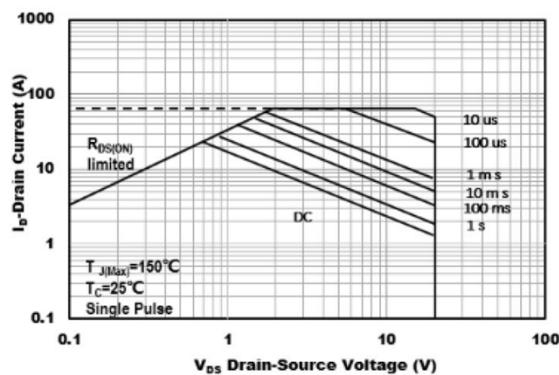


Figure7. Safe Operation Area

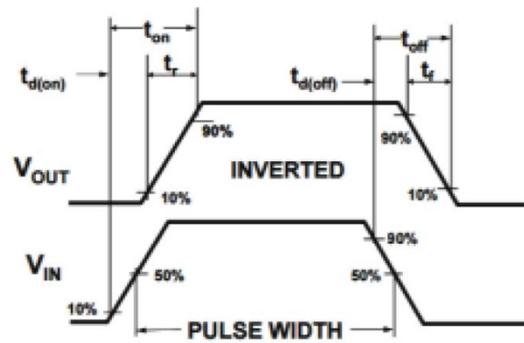


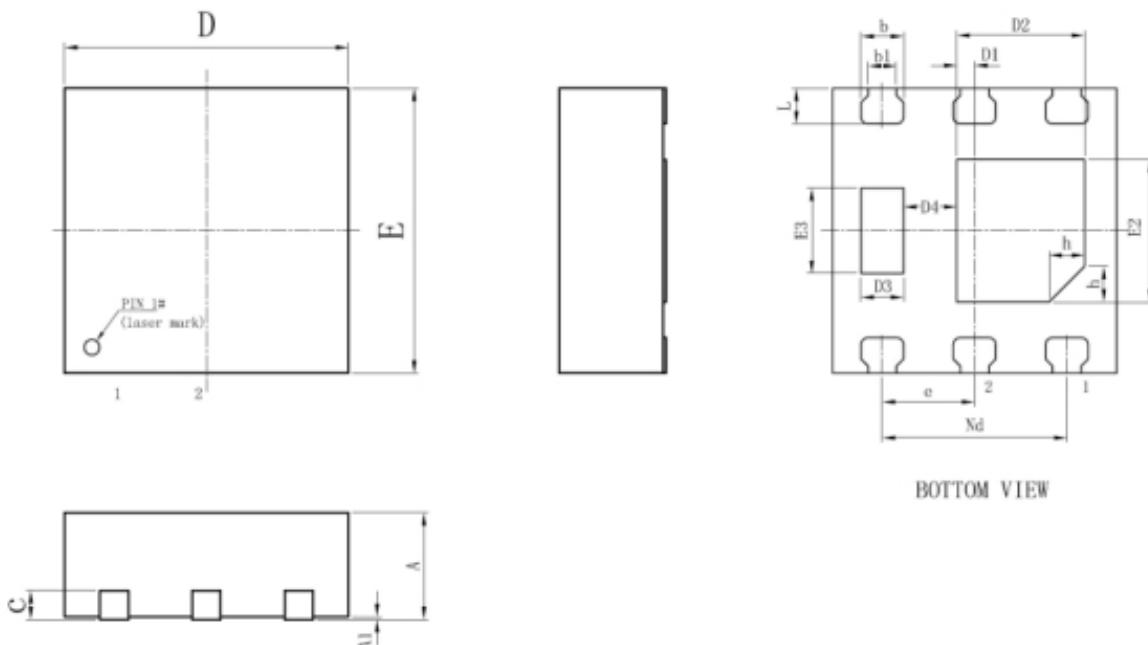
Figure8. Switching wave



ZL MOSFET

ZL1216

## DFN2\*2-6L-J Package Information



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1		0.02	0.05
b	0.25	0.30	0.35
b1		0.20REF	
c		0.203REF	
D	1.90	2.00	2.10
D1	0.08	0.125	0.18
D2	0.85	0.90	0.95
D3	0.25	0.30	0.35
D4	0.33	0.375	0.43
e		0.65BSC	
Nd		1.30BSC	
E	1.90	2.00	2.10
E2	0.95	1.00	1.05
E3	0.55	0.60	0.65
L	0.20	0.25	0.30
h		0.25REF	